The 19th U.S.-Korea Forum on Nanotechnology

Professor. Hak-Sung Kim

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Professor Hak-Sung Kim received his Ph.D. in Mechanical Engineering from KAIST in 2006. From 2006 to 2008, he worked at Samsung Electronics' Semiconductor Packaging Center as a senior researcher. He then continued his academic career as a postdoctoral researcher and lecturer at the University of California, Los Angeles (UCLA) from 2008 to 2010. Since 2010, he has been a faculty member in the Department of Mechanical Engineering at Hanyang University.

For over 20 years, Professor Kim has been actively engaged in advanced semiconductor packaging research. Since 2022, he has served as the Director of the Hanyang Advanced Semiconductor Packaging Center, where he leads multidisciplinary research efforts focused on next-generation semiconductor packaging technologies.

His main research themes include:

- Development of innovative processes for semiconductor packaging
- Characterization and reliability analysis of packaging materials
- AI-driven prediction and modeling of packaging warpage and deformation

Professor Kim is recognized for bridging mechanical engineering fundamentals with advanced electronic packaging applications, contributing to both academic advancements and industrial innovations in semiconductor packaging.